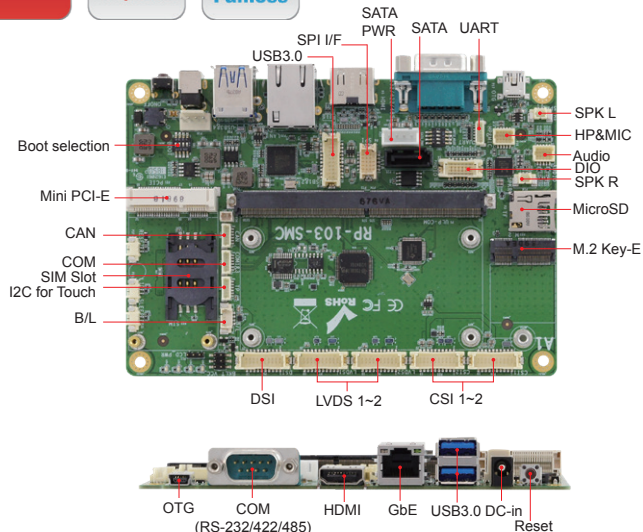




SMARC
module



System

Form Factor	Carrier Board Compliant with SMARC™ V2.0
I/O	1x 12~24V DC-in Jack 1x RJ45 Gigabit LAN 2x USB3.0 1x OTG Micro USB2.0 1x HDMI 2.0 1x COM (RS232/422/485 by switch)
Internal Headers/Connectors	1x 12~24V DC-in header 2x CAN bus 2.0b 1x 18/24-bit Dual Channel LVDS 1x LCD backlight 2x MIPI-CSI2 1x MIPI-DSI 2x USB3.0 1x 12 GPIOs 2x RS232 (RX/TX only) 1x I2C 1x SATA II and power 1x I2S 2x SPI 1x Full size Mini PCI-E 1x SIM socket 1x M.2 Key-E (2230) 1x MicroSD slot 1x HP&MIC 1x Audio 1x Speaker R and L 1 x Reset 1x UART
Jumpers, Switches & Buttons	1x Boot select switch 1x Power button 1x Backlight power (3V3/5V/12V) switch 1x LCD power 3V3/5V switch
Dimensions	147mm x 102mm (5.8" x 4")

Features

- Carrier Board for RM-N8M and RM-N8MMI series SMARC™ 2.0 CPU Module
- Rich peripheral I/O support
- Validated with Yocto v2.5 and Android 9
- Complete system available for evaluation

Environment	Humidity: 0 % to 90 % RH at 60°C (non-condensing) Shock: Non-Operating: 1G, 15 mins (x-, y-, z-axis) Vibration: Non-operating: 3Hz to 500Hz, 15 mins
Operating Temperature	-40°C ~ 85°C
OS Support	Depending on the CPU module
Certification	CE/FCC Class B

Ordering Information

RP-103-SMC (Carrier Board)	3.5" SMARC 2.0 carrier board, 2-CH LVDS, HDMI, 2x CSI, DSI, GbE, RS-234/422/285, USB3.0, M.2 Key-E (2230), Mini PCI-E w/ SIM socket, USB OTG, SATA, CAN, Audio/Speaker out/HP&MIC, MicroSD and 12~24VDC
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